PCN Number:			20220628001.1					ı	PCN Date:	June 28, 2022		
Title: Qualification			of TI Taiwan as an additional Assembly site for select devices					es				
Cus	tome	Contact:	PCN Ma	CN Manager Dept: Quality Se			rvic	vices				
Proposed 1 st Ship Date			e: Se	ept 28, 2022 Sample requests accepted until			July 28, 2022*					
*Saı	mple r	ed afte	ed after (July 28, 2022) will not be supported.									
Change Type:												
Assembly Site					Design				Wafer Bum	p Site		
Assembly Process						Data Sheet				Wafer Bum	p Material	
Assembly Materials			}			Part number change			Wafer Bump Process			
Mechanical Specificati			ation			Test Site				Wafer Fab Site		
Packing/Shipping/Labeling]		Test Process			Wafer Fab Materials				
					•					Wafer Fab	Process	
_	PCN Details											

Description of Change:

Texas Instruments is pleased to announce the qualification of TI Taiwan as additional Assembly Site for Select Devices listed in the "Product Affected" Section. No material differences between sites.

Assembly Site	Assembly Site Origin	Assembly Country Code	Assembly City
TI Malaysia	MLA	MYS	Kuala Lumpur
TI Taiwan	TAI	TWN	Chung Ho, New Taipei City

Reason for Change:

Continuity of supply.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
	$oxed{\boxtimes}$ No Change	No Change	

Changes to product identification resulting from this PCN:

Assembly Site		
TI Malaysia	Assembly Site Origin (22L)	ASO: MLA
TI Taiwan	Assembly Site Origin (22L)	ASO: TAI

Sample product shipping label (not actual product label)





(1P) SN74LS07NSR (a) 2000 (D) 0336 (31T)LOT: 3959047MLA 4W) TKY(1T) 7523483S12 (2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO:USA (22L) ASO: MLA (23L) ACO: MYS

Product Affected:

Qualification Report

Approve Date 24-May-2022

Qualification Results

Туре	Test Name / Condition	Duration	Qual Device: DRV8848PWPR	QBS Product Reference: DRV8846RGER	QBS Product Reference: DRV8848PWP	QBS Process Reference: TPS62110RSA	QBS Package Reference: DRV8818PWP
-	AT MQ	(per mfg. Site specification)	1/Pass	-	•	-	-
AC	Autoclave 121C	240 Hours	-	-	-	3/231/0	-
AC	Autoclave 121C	96 Hours	-	-	-	3/231/0	3/231/0
CDM	ESD - CDM	1500 V	-	1/3/0	1/3/0	-	-
DPA	Destructive Physical Analysis	Post 500 Temp Cycle	-	-	1	1	-
ED	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0	1	-
ELFR	Early Life Failure Rate, 140C	48 Hours	-	-	-	3/1881/0	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	-	3/231/0	3/231/0
HBM	ESD - HBM	4000 V	-	1/3/0	-	-	-
HTOL	Life Test, 140C	480 Hours	-	-	-	3/231/0	-
HTOL	Life Test, 155C	240 Hours	-	-	-	-	-
HTSL	High Temp Storage Bake 170C	420 Hours	-	-	-	3/231/0	3/231/0
LU	Latch-up	(per JESD78)	-	1/6/0	-	-	-
TC	Temperature Cycle, -65/150C	1000 Cycles	-	1/77/0	-	3/231/0	-
TC	Temperature Cycle, -65/150C	500 Cycles	-	1/77/0	1/77/0	3/231/0	3/231/0

- QBS: Qual By Similarity
- Qual Device DRV8848XXXPWP is qualified at LEVEL3-260CG
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
WW PCN Team	PCN www admin_team@list.ti.com

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